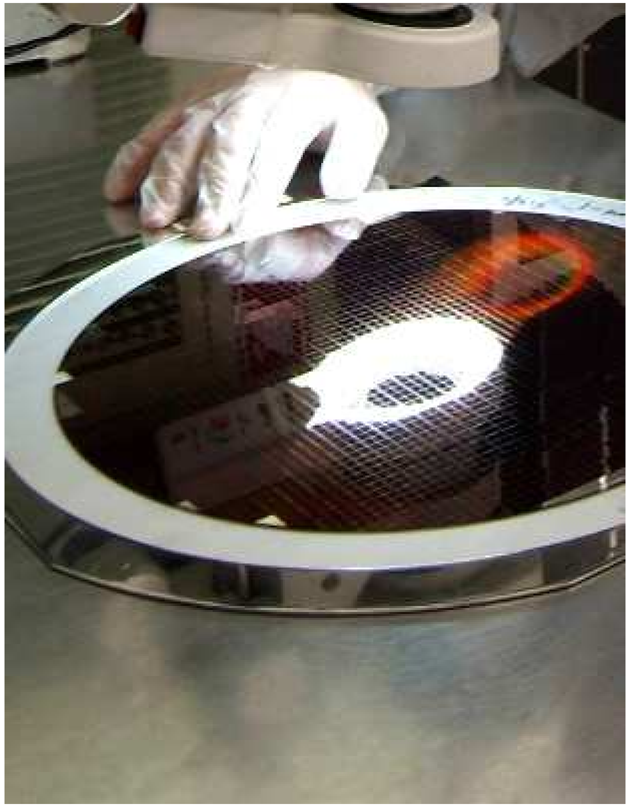
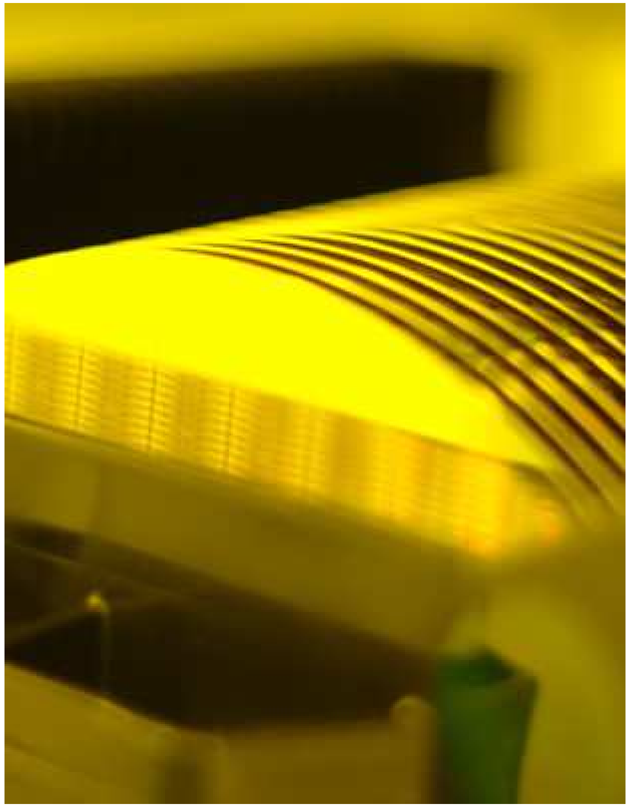




ChipMOS

Industry Leading Provider of Outsourced Semiconductor Assembly, Test & Bumping Services

July, 2017

Safe Harbor Notice

- This presentation contains certain forward-looking statements. These forward-looking statements may be identified by words such as ‘believes,’ ‘expects,’ ‘anticipates,’ ‘projects,’ ‘intends,’ ‘should,’ ‘seeks,’ ‘estimates,’ ‘future’ or similar expressions or by discussion of, among other things, strategy, goals, plans or intentions. These statements include financial projections and estimates and their underlying assumptions, statements regarding plans, objectives and expectations with respect to future operations, products and services, and statements regarding future performance. Actual results may differ materially in the future from those reflected in forward-looking statements contained in this document, due to various factors. Actual results may differ materially in the future from those reflected in forward-looking statements contained in this document, due to various factors. Further information regarding these risks, uncertainties and other factors are included in the Company’s most recent Annual Report on Form 20-F filed with the U.S. Securities and Exchange commission (the “SEC”) and in the Company’s other filings with the SEC.

ChipMOS

Group Snapshot

Overview

- **Founded:** 1997
- **Headquarters:** Hsinchu, Taiwan
- **Ticker Symbol:** TWSE : 8150.TW
  NASDAQ : IMOS (ADS)
- **Employees[1]:** Taiwan: 5,577
- China: 784

Manufacturing footprint in China & Taiwan

Shanghai, China
ChipMOS Shanghai
(JV with Unigroup)

Hsinchu, Taiwan
ChipMOS Taiwan

Tainan, Taiwan
ChipMOS Taiwan

Key milestones

2000
- Started TCP package for LCD driver IC and 12" wafer assembly and testing business

2001
- IMOS became the first Taiwanese semiconductor OSAT company listed on the Nasdaq Stock Market

2010
- Acquired DDIC assets of SPIL
- SPIL became a strategic shareholder of ChipMOS Taiwan

2011
- Set up 12" Gold bumping, Cu RDL, MCP, Cu pillar, MCB bumping and WLCSP line

2014
- Listed ChipMOS Taiwan on TWSE
- Announced the merger between ChipMOS Taiwan and ThaiLin
- Invested in JMC and Ryowa

2015
- ChipMOS Taiwan merged ThaiLin[2]
- Announced strategic partnership with Tsinghua Unigroup

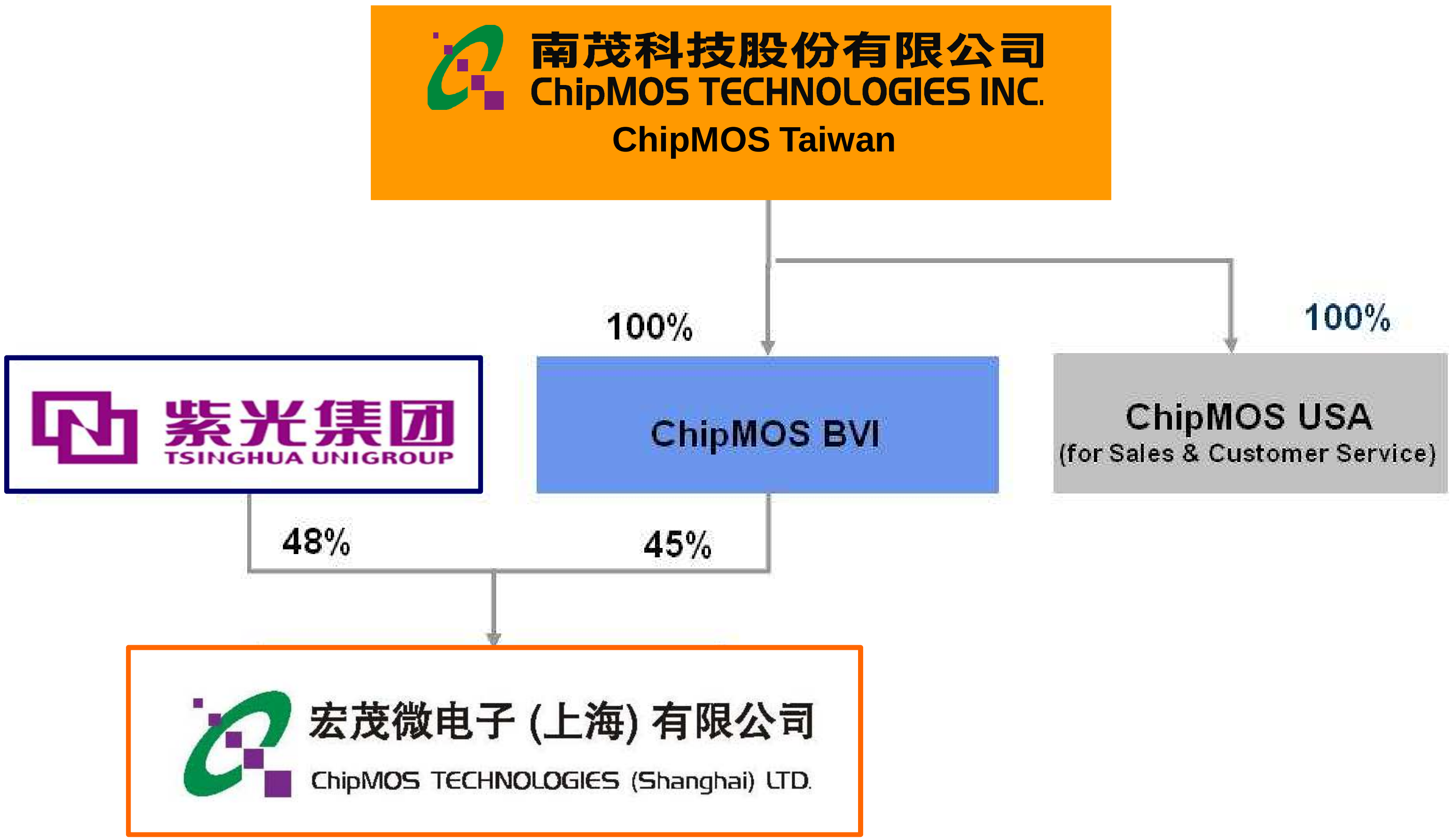
2016
- ChipMOS Taiwan merged ChipMOS Bermuda and issued ADS (Nasdaq Ticker: IMOS)

2017
- ChipMOS Taiwan formed Shanghai JV with Tsinghua Unigroup [3]

(1) As of March 31, 2017
(2) ThaiLin was listed on OTC since Oct 2000, and was de-listed in Jun 2015
(3) ChipMOS Taiwan is authorized by Unigroup to manage ChipMOS Shanghai

ChipMOS

Corporate Holding Structure



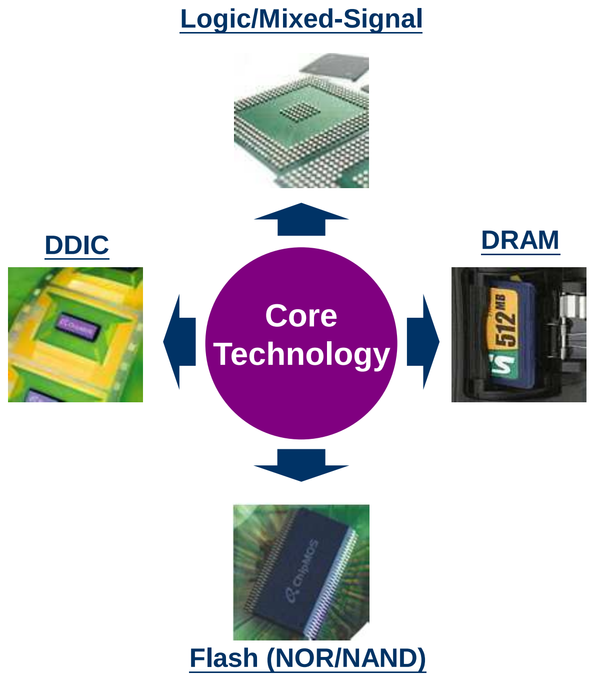
Industry Leader in Outsourced Semiconductor Assembly & Test

1. Leveraging Leadership Position and Track Record as Top Service Provider
2. Focused on Growth in Key Markets, including DDIC, Memory & Mixed Signal Markets
3. Joint-Venture to Monetize Shanghai Operation, Drive China Growth and Deliver Increased Profitability in 2017 and Beyond
4. Start to Realize Significant Financial and Operational Benefits in 2017 Post Corporate Structure Streamlining Completed
5. Robust Technology Roadmap Supports Multiple Growth Vectors, Including Finger Print Sensors, MEMS, Mixed-Signal, and Power IC Market Segments
6. Proven Senior Management Team Executing on Business Strategies

Focus on Higher Margin Growth Markets

- Focus on specialty end markets
- Leading-edge turn-key solutions for high-growth applications
- Core technology drives innovation and cost-savings for customers

Core Technology



Turnkey, High-yield, OSAT Partner of Choice

- Offer turn-key solutions for core technology product segments
- Dedicated OSAT capacity and strategically focused on collaboration-driven growth
- Leverage current partnerships to capture new customers
- Targeting mixed-signal, finger print sensor, power management IC and MEMS for expansion

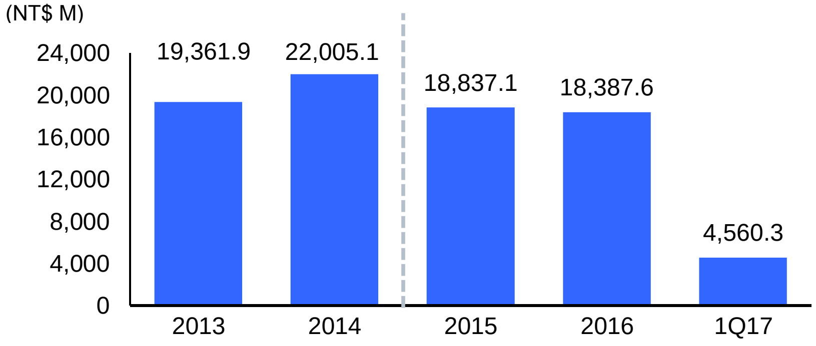
Services Provided

Product Offering

	Bumping /RDL	Wafer Test	Assembly/Package	Product Test	Key End Markets
DDIC	◆	◆	◆	◆	
Flash	◆	◆	◆	◆	
DRAM	◆	◆	◆	◆	
Logic/Mixed Signal	◆	◆	◆	◆	

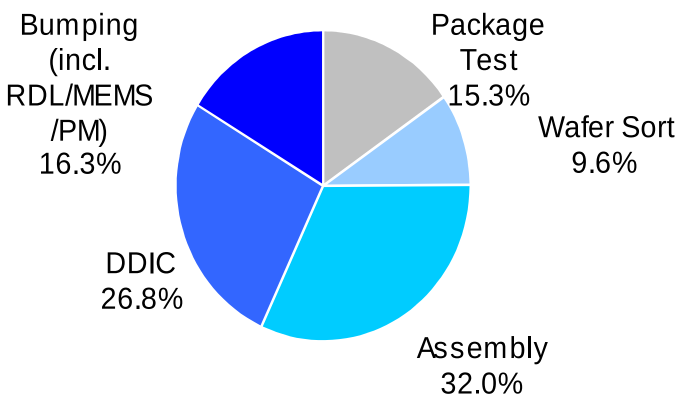
2016 Revenue Breakdown

Consolidated Revenue

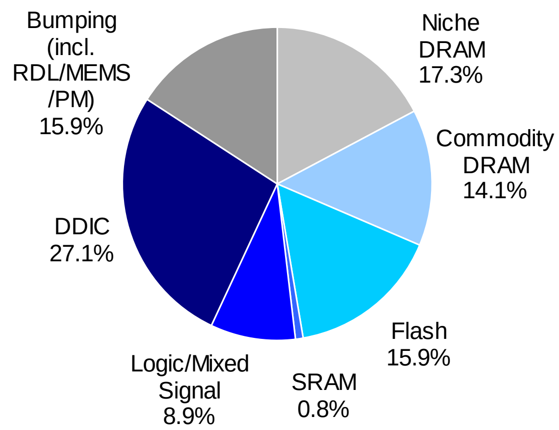


2016 Revenue Breakdown；2016 Consolidated Revenue NT$ 18,387.6M

By Manufacturing Segments



By Products

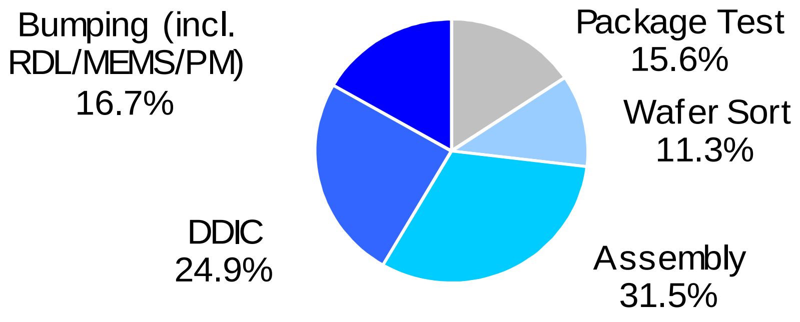


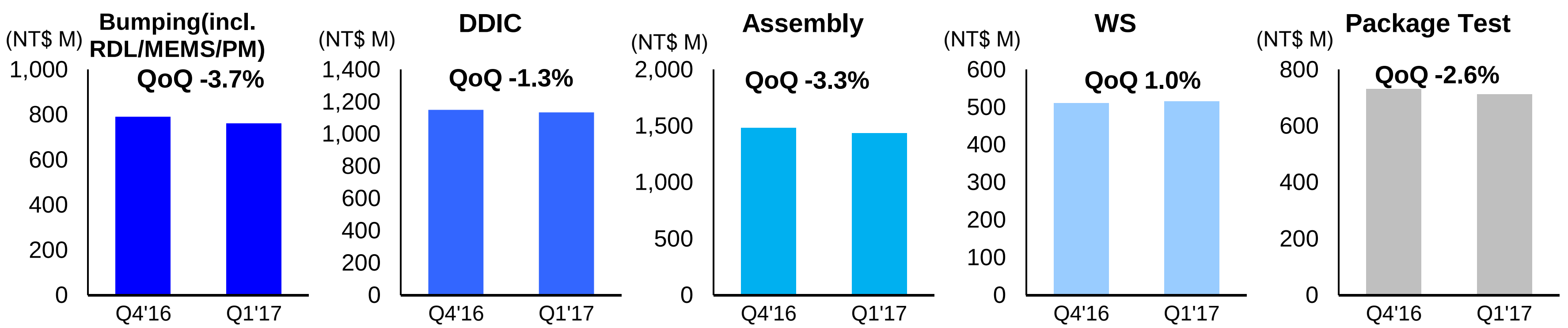
(1) *Since 2015, ChipMOS' Shanghai's revenue was not included in the consolidated revenue.*

ChipMOS

1Q17 Revenue Breakdown (unaudited)

By Manufacturing Segments

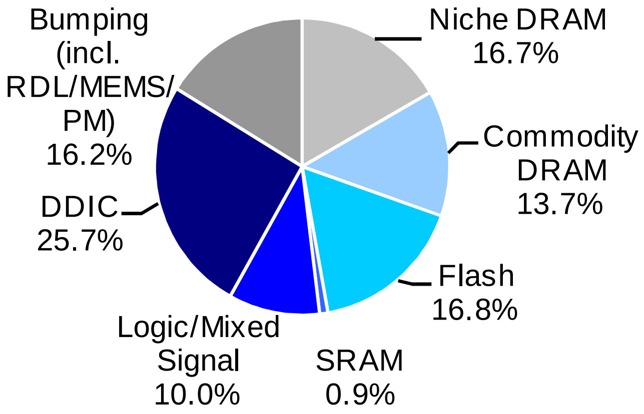


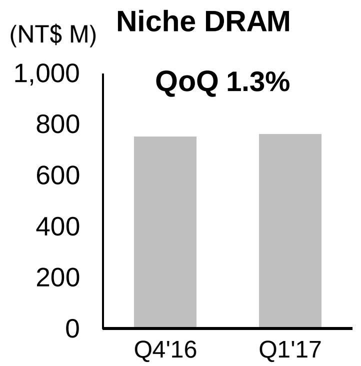


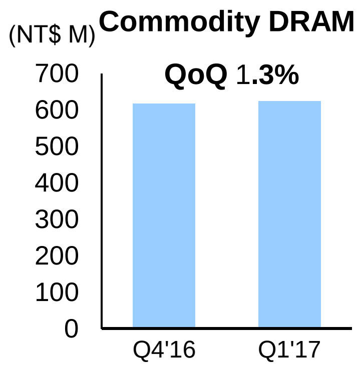
ChipMOS

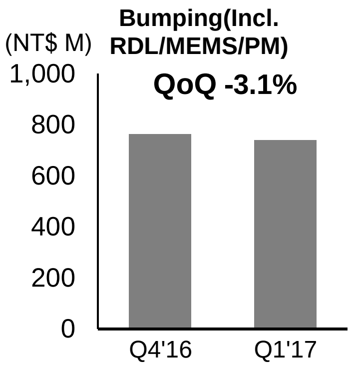
1Q17 Revenue Breakdown (unaudited)

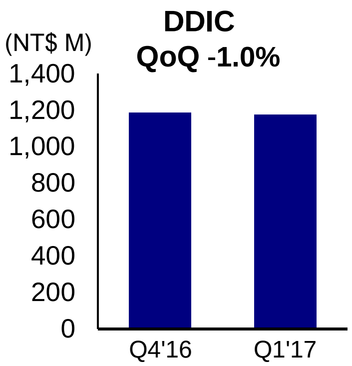
By Products

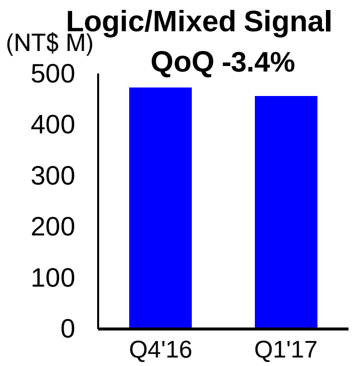


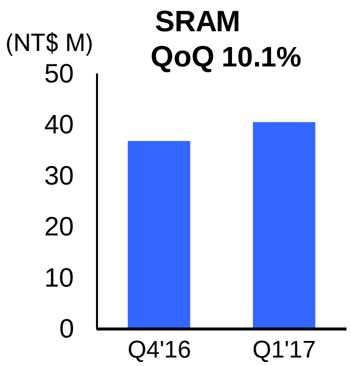


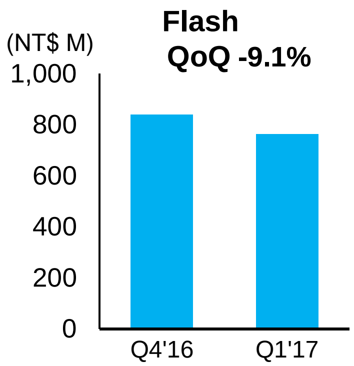












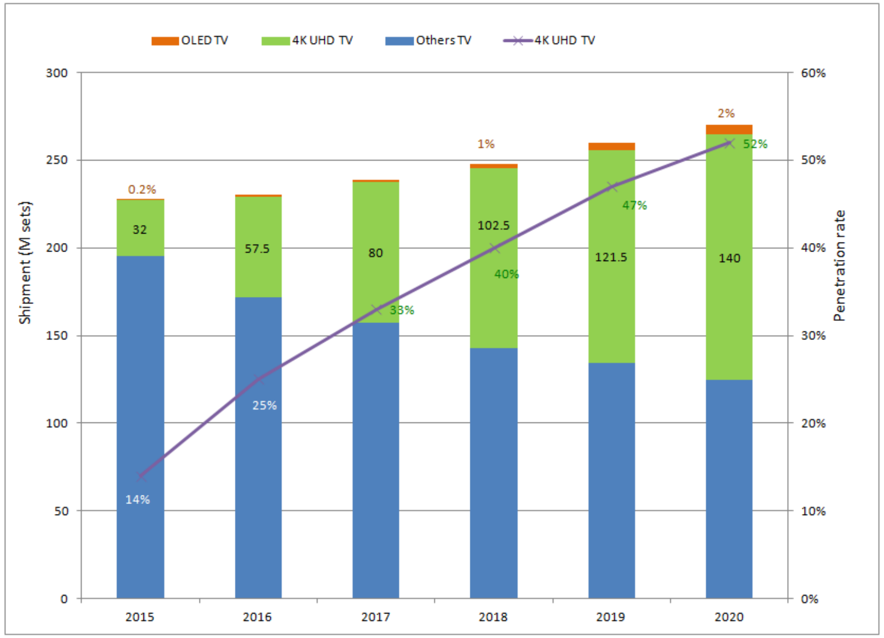
ChipMOS

Well-positioned to Capture the DDIC Outsourcing Markets

- Global proliferation of digital broadcasting fosters adoption of DDIC TVs
- Widespread use of DDIC in electronic products
- High resolution / function integration to drive DDIC growth
- ChipMOS is one of the major players in the DDIC bumping and assembly / test market
- Focused capacity investment in growth market to facilitate 4K, OLED and TDDI transitions
- Develop bumping technology for non-DDIC applications to capture new business and enable turn-key offerings in mixed signal, IoT, sensor markets

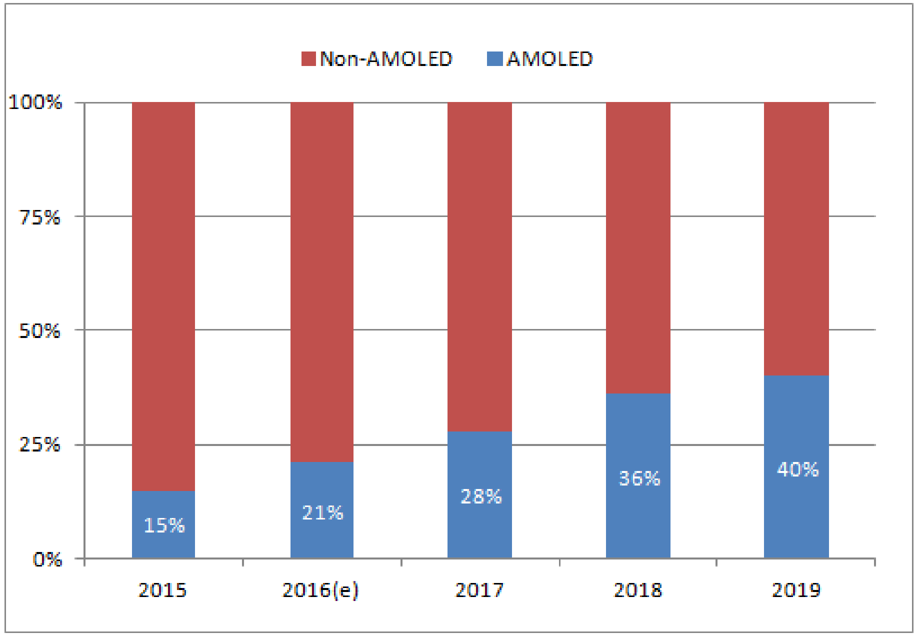
UHD TV & OLED to Grow DDIC COF Capacity Demand

2015 - 2020 UHD TV growth



Source: Futuresource consulting, Apr.'2016 & HIS market Jan.'2017

AMOLED Penetration in Global Smartphone



Source: WitsView consulting, Jul.'2016

- **UHD(4K) TV & OLED propel significant memory/storage market growth in set top boxes, TV, home entertainment system**
- **Market penetration of UHD TV & OLED panel accelerating**
- **Increase in DDIC COF demand driven by UHD TV and AMOLED**

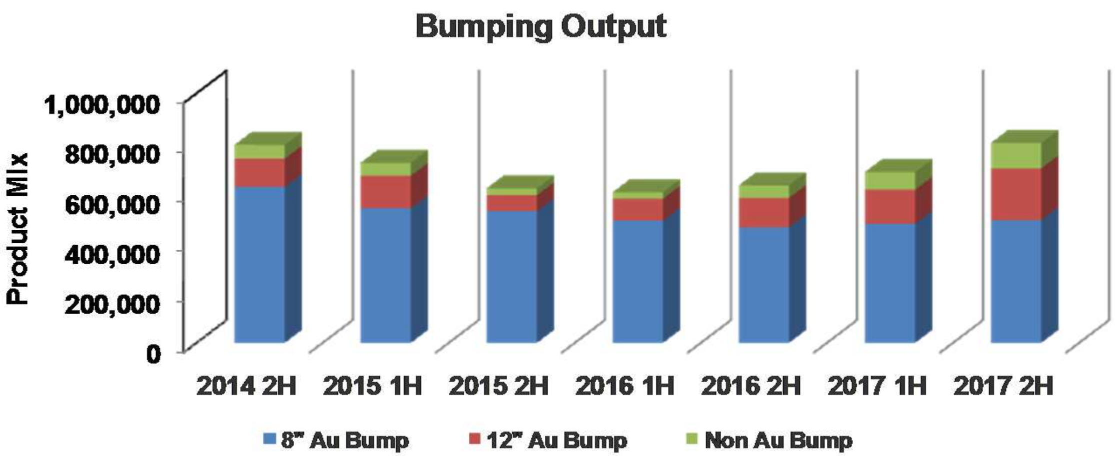
ChipMOS preparing capacity to capture market growth

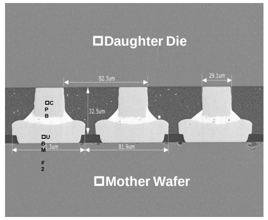
ChipMOS

Extend Bumping Core Competency to Grow New Business

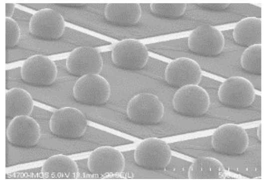
- 4K/UHD penetration rate at 3x faster than that of FHD; To increase display driver output to meet both 4KTV and AMOLED demand

- Extending core competency to capture new market of Non-driver bumping products and provide turn key solutions for: Flip Chip, Advanced Memory, RDL, WLCSP, Power Management IC, etc.

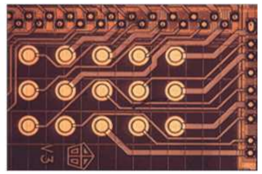




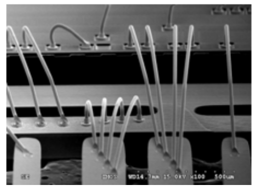
Flip Chip (CoW)



WLCSP



RDL

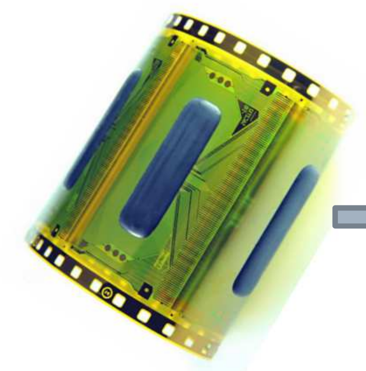


Universal Flash Storage (UFS)

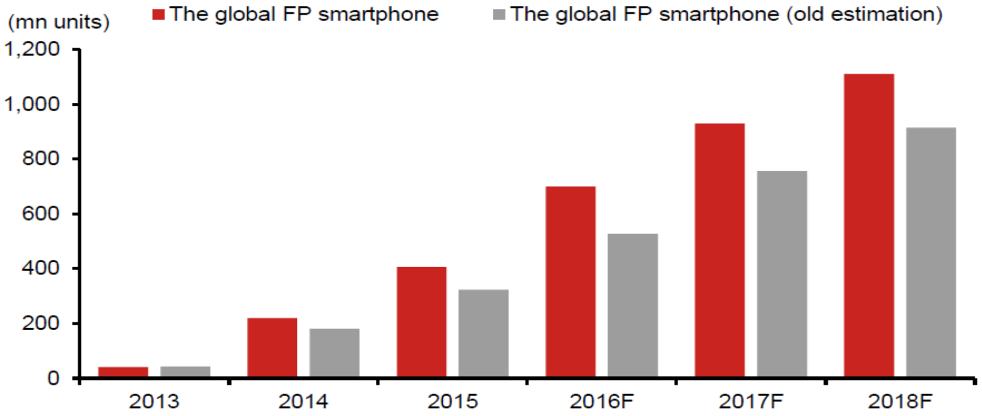
ChipMOS

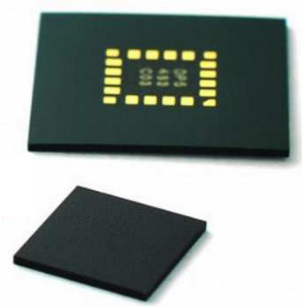
Fingerprint Sensor Demand Propelled by Mobile Products

- By offering both LGA and COF (tape based) products, ChipMOS is uniquely positioned by providing both types of packages to support FPS market growth
- 10+ years of FPS(COF) packaging experience
- Full range of options support turn-key solutions with maximum technology extendibility



COF Package





LGA Package

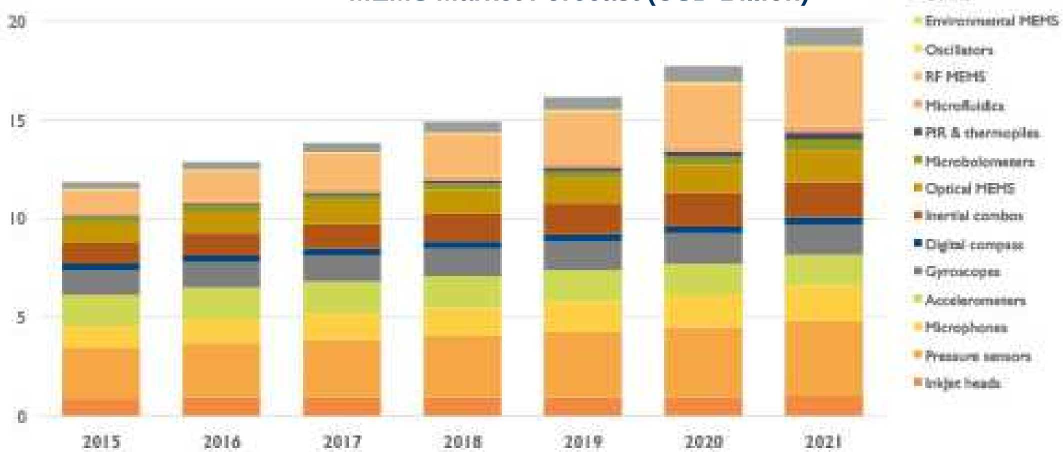
Source: Nomura estimates

ChipMOS

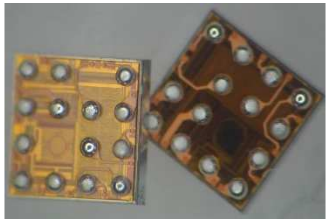
MEMS Market Growth Leads to Turn-key Service Opportunities

- MEMS industry growth driven mainly by applications such as smartphone, mobile consumers products, medical and automotive market
- Deliver Package and Wafer based products plus comprehensive test services, ChipMOS established itself as a turn-key OSAT provider to the growing MEMS market
- 6+ years record of executing magnetometer backend turn-key service for key customers
- Built capabilities to cover gyroscope, accelerometers & pressure sensors

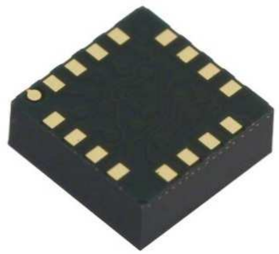
MEMS Market Forecast (USD Billion)



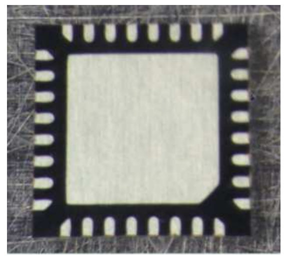
Source: Yole Development



WLCSP Magnetometer



LGA Package

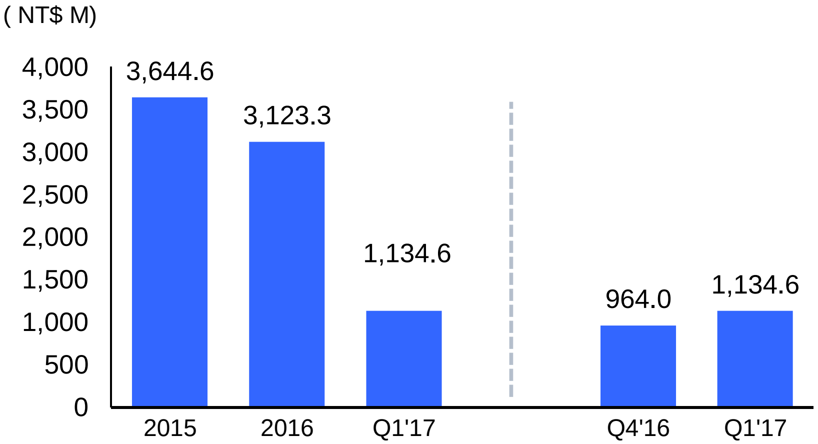


QFN Package

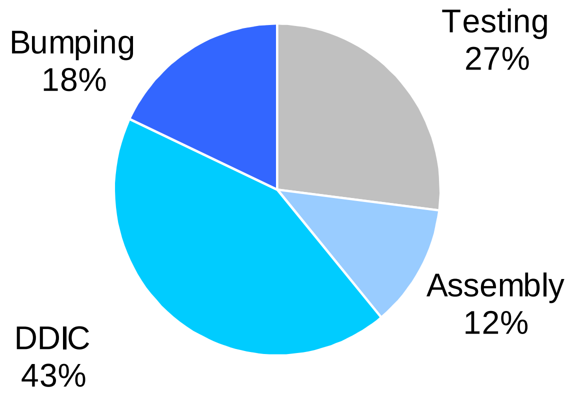
Financial Highlights

1Q17 Capital Expenditures (unaudited)

CapEx

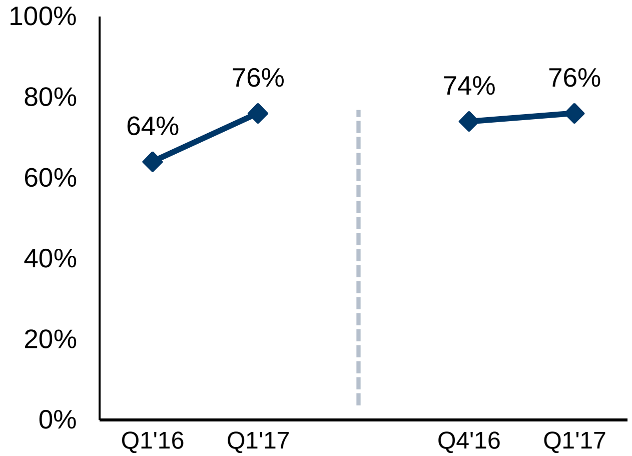


1Q17 CapEx Breakdown

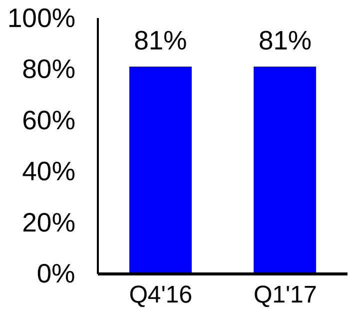


1Q17 Capacity Utilization

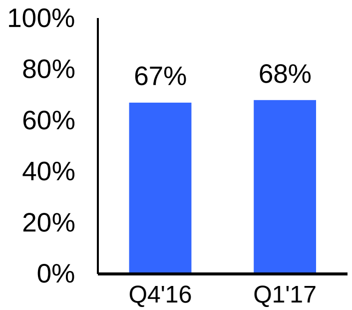
Utilization Rate



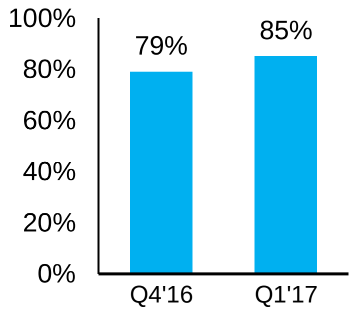
Testing



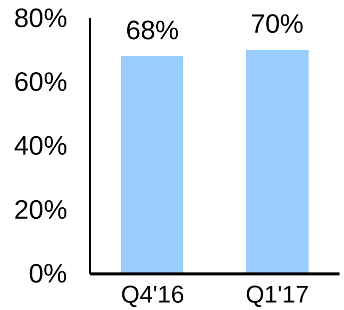
Assembly



DDIC



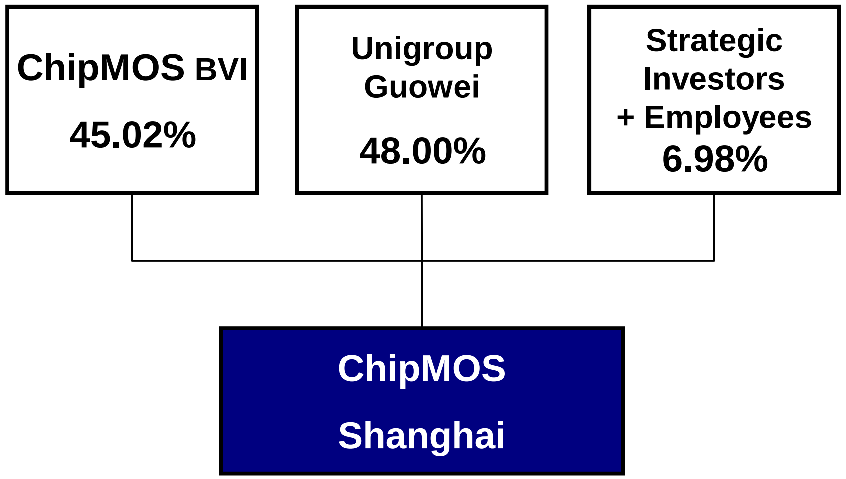
Bumping



China JV: Catalyst for Significant Profitability Growth

- Strategic investors led by Tsinghua Unigroup have invested RMB 498.43 million for a 54.98% stake in ChipMOS Shanghai. The JV deal closed on March 24, 2017.
- All together, ChipMOS Shanghai is expected to receive a total approximately RMB 1,074 million in funding by the end of 2017.
- ChipMOS will not consolidate ChipMOS Shanghai post the JV closure. ChipMOS Shanghai will become a long-term investment of ChipMOS and recognized profit/loss generated pro rata.
- ChipMOS is strategically positioned to capture the growth opportunities of the semiconductor market in China

Post-Transaction Shareholding Structure



Management Team with Deep Industry Experience

Shih-Jye CHENG – Chairman & President

- 32 Years of industry experience
- Former head of the back-end operation of Mosel
- Former Chairman of Chantek
- Former Chairman of AMCT
- Former board director of Ultima Electronics Corp
- MBA from Saginaw Valley State University

Dr. Shou-Kang CHEN - CFO

- 28 Years of industry experience
- IR officer, head of the finance division, and former head of strategy development, and head of the quality lab in the firm
- B.S. of Mining and Petroleum Engineering and M.S. and Ph.D. from the School of Mining, Metallurgy, Material Science of National Cheng Kung University

Peter KU – Special Assistant

- 43 Years of industry experience
- Former board director of ThaiLin
- Former President of Shanghai
- Former VP of ChipMOS Taiwan
- Former VP of Microchip Taiwan Branch
- M.S. of Electrical Engineering from National Cheng Kung University

Dr. David WANG – VP of Strategy & IR

- 34 Years of industry experience
- Former VP of Fibera
- Former Senior Director at Lam Research
- Former IBM's Microelectronics Senior Engineer/ Manager
- M.S. and Ph.D. from the University of Michigan and B.S. of Science from Fu Jen University

Lafair CHO – COO

- 23 Years of industry experience
- Former President of ThaiLin
- Former VP of the IC testing of ChipMOS Taiwan
- Former manager of production material control of Mosel
- M.S. of Industrial Management from National Cheng Kung University

Steve CHENG – President of U.S.

- 17 Years of industry experience
- Former President and CFO of ChipMOS U.S.A.
- B.S. of Business Banking and Insurance from Feng Chia University

Paul YANG – President of Shanghai

- 17 Years of industry experience
- Former VP of Test Production Group
- Former VP of the deputy assistant and mix-signal test division of ThaiLin
- M.S of Electrical Engineering from National Cheng Kung University

Company Website

- http://www.chipmos.com